



# Final Product/Process Change Notification

Document #:FPCN25811X

Issue Date:10 Jun 2024

<b>Title of Change:</b>	Transfer Backgrind/Backmetal Site from JS Foundry Niigata, Japan to onsemi ISMF, Malaysia for SOT23 and SC88 Product	
<b>Proposed First Ship date:</b>	17 Sep 2024 or earlier if approved by customer	
<b>Contact Information:</b>	Contact your local onsemi Sales Office or <a href="mailto:guokun.yeng@onsemi.com">guokun.yeng@onsemi.com</a>	
<b>PCN Samples Contact:</b>	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
<b>Additional Reliability Data:</b>	Contact your local onsemi Sales Office or <a href="mailto:NurulAkmar.MohdFauzi@onsemi.com">NurulAkmar.MohdFauzi@onsemi.com</a>	
<b>Type of Notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a>	
<b>Marking of Parts/ Traceability of Change:</b>	Lot traceability will identified by datecode	
<b>Change Category:</b>	Wafer Fab Change	
<b>Change Sub-Category(s):</b>	Manufacturing Site Transfer	
<b>Sites Affected:</b>		
<b>onsemi Sites</b>	<b>External Foundry/Subcon Sites</b>	
onsemi, ISMF Malaysia	None	

**Description and Purpose:**

This Product Change Notification is to notify customers that onsemi is transferring the back grind and back metal process for Mosfet technology in SOT23 and SC88 packages to the onsemi ISMF site located in Seremban, Malaysia.

	From	To
<b>Back Grind Back Metal Site</b>	onsemi Bucheon, South Korea JS Foundry, Japan	onsemi Bucheon, South Korea onsemi ISMF, Malaysia

No change to orderable part number.

There is no product marking change as a result of this change.



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## Reliability Data Summary:

QV DEVICE NAME: **FDG6303N**

RMS: **S91927**

PACKAGE: **SC88**

Test	Specification	Condition	Interval	Result
HTGB	JESD22-A108	Tj = 150C, bias = 100% of rated V	1008 hours	0/231
HTRB	JESD22-A108	Tj = 150C, bias =100% of rated V (Not to exceed max rated)	1008 hours	0/231
PC	J STD 020, JESD22-A113	IR reflow at 245C or 260C (pkg dependant)		0/924
HAST+PC	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, bias = 80% of rated V or 100V max	96 hours	0/231
TC+PC	JESD22-A104	Temp = -55°C to +150°C; for 1000 cycles	1000 cycles	0/231
UHASt+ PC	JESD22-A118	Temp = 130C, RH=85%, ~ 18.8 psig	96 hours	0/231
IOL + PC	MIL STD750, M 1037 AEC Q101	Ta=+25°C, deltaTj=100°C max, 2 min= Ton=Toff (pkg dependent)	15000 cycles	0/231
SAT	12MSB17722C	12MSB17722C		0/66

## Electrical Characteristics Summary:

Electrical characteristics are not impacted.

## List of Affected Parts:

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
FDG8850NZ	FDG6303N
FDG6322C	FDG6303N
FDG6304P	FDG6303N
FDG6321C	FDG6303N
FDG1024NZ	FDG6303N
FDG6332C	FDG6303N
FDG6335N	FDG6303N
FDG6303N	FDG6303N
FDG6301N	FDG6303N
FDG6317NZ	FDG6303N